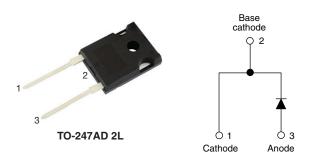


Ultrafast Soft Recovery Diode, 60 A FRED Pt®



PRIMARY CHARACTERISTICS					
I _{F(AV)}	60 A				
V _R	600 V				
V _F at I _F	1.11 V				
t _{rr} typ.	See Recovery table				
T _J max.	175 °C				
Package	TO-247AD 2L				
Circuit configuration	Single				

FEATURES

- · Ultrafast recovery time
- Low forward voltage drop
- 175 °C operating junction temperature
- AEC-Q101 qualified, meets JESD 201 class 1A whisker test





ROHS

HALOGEN FREE

BENEFITS

- · Reduced RFI and EMI
- Higher frequency operation
- Reduced snubbing
- · Reduced parts count

DESCRIPTION / APPLICATIONS

These diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems.

The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for HF welding, power converters and other applications where switching losses are not significant portion of the total losses.

ABSOLUTE MAXIMUM RATINGS							
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS			
Cathode to anode voltage	V _R		600	V			
Continuous forward current	I _{F(AV)}	T _C = 116 °C	60				
Single pulse forward current	I _{FSM}	T _C = 25 °C	600	Α			
Maximum repetitive forward current	I _{FRM}	Square wave, 20 kHz	120				
Operating junction and storage temperatures	T _J , T _{Stg}		-55 to +175	°C			

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Breakdown voltage, blocking voltage	V _{BR} , V _R	Ι _R = 100 μΑ	600	-	-		
Forward voltage	V _F	I _F = 60 A	-	1.35	1.68	V	
		I _F = 60 A, T _J = 125 °C	-	1.20	1.42		
		I _F = 60 A, T _J = 175 °C	-	1.11	1.30		
Reverse leakage current	I _R	V _R = V _R rated	-	-	50		
		T _J = 150 °C, V _R = V _R rated	-	-	500	μΑ	
Junction capacitance	C _T	V _R = 600 V	-	39	-	pF	



DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	MIN.	TYP.	MAX.	UNITS		
		$I_F = 1 A, dI_F/dt = 20$	I _F = 1 A, dI _F /dt = 200 A/µs, V _R = 30 V		34	45		
Reverse recovery time	t _{rr}	T _J = 25 °C		-	81	-	ns	
		T _J = 125 °C	$I_F = 60 \text{ A}$ $dI_F/dt = 200 \text{ A/}\mu\text{s}$ $V_R = 200 \text{ V}$	-	164	-		
Peak recovery current	I _{RRM}	T _J = 25 °C		-	7.4	-	Α	
		T _J = 125 °C		-	17.0	-		
Reverse recovery charge	Q _{rr}	T _J = 25 °C		-	300	-	nC	
		T _J = 125 °C		-	1394	-		

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Thermal resistance, junction to case	R _{thJC}		-	-	0.63	17.004
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth and greased	-	0.2	-	- K/W
Weight			-	5.5	-	g
			-	0.2	-	OZ.
Mounting torque			1.2 (10)	-	2.4 (20)	N ⋅ m (lbf ⋅ in)
Marking device		Case style TO-247AD 2L		60EPU06L		

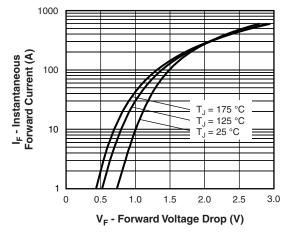


Fig. 1 - Typical Forward Voltage Drop Characteristics

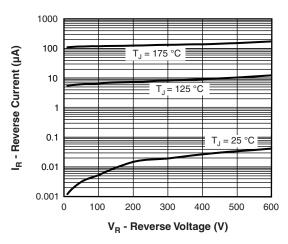


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

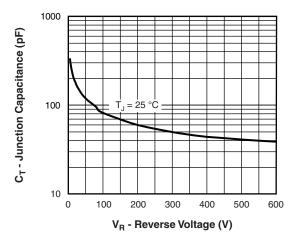


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

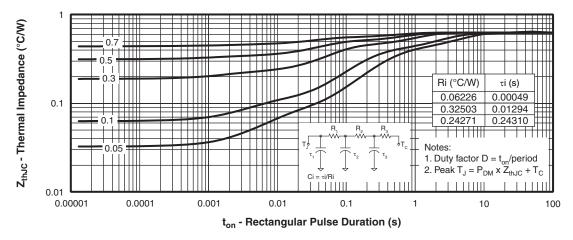


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

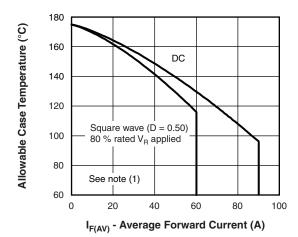
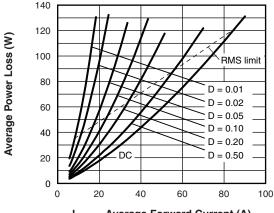


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current



I_{F(AV)} - Average Forward Current (A) Fig. 6 - Forward Power Loss Characteristics

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Note

Revision: 09-Jul-2019

Formula used: $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$; Pd = Forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 6); Pd_{REV} = Inverse power loss = $V_{R1} \times I_{R} (1 - D)$; I_{R} at V_{R1} = 80 % rated V_{R}

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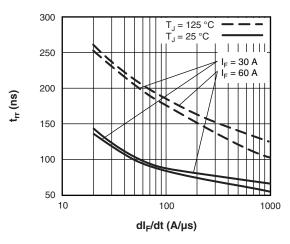


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

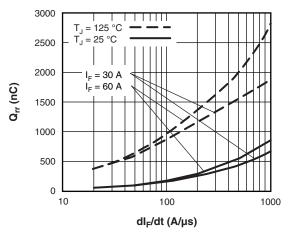
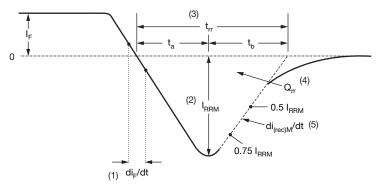


Fig. 8 - Typical Stored Charge vs. dl_F/dt



- (1) di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) $\rm t_{rr}$ reverse recovery time measured from zero crossing point of negative going $\rm I_F$ to point where a line passing through 0.75 $\rm I_{RRM}$ and 0.50 $\rm I_{RRM}$ extrapolated to zero current.
- (4) $\mathbf{Q}_{\rm rr}$ area under curve defined by $\mathbf{t}_{\rm rr}$ and $\mathbf{I}_{\rm RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

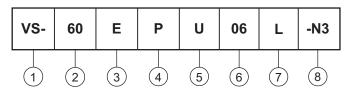
(5) di_{(rec)M}/dt - peak rate of change of current during t_b portion of t_{rr}

Fig. 9 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE

Device code



- 1 Vishay Semiconductors product
- 2 Current rating (60 = 60 A)
- 3 Circuit configuration:
 - E = single diode
 - A = single diode, 3 pins
- 4 P = TO-247
- 5 U = ultrafast recovery
- 6 Voltage rating (06 = 600 V)
- 7 L = long lead
- 8 Environmental digit:
 - -N3 = halogen-free, RoHS-compliant and totally lead (Pb)-free

ORDERING INFORMATION (Example)						
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION			
VS-60EPU06L-N3	25	500	Antistatic plastic tube			

LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?95536			
Part marking information	www.vishay.com/doc?95648			
SPICE model	www.vishay.com/doc?95545			

TO-247AD 2L

DIMENSIONS in millimeters and inches



View B

SYMBOL	MILLIN	MILLIMETERS		INCHES	
SYMBOL	MIN.	MAX.	MIN.	MAX.	NOTES
А	4.65	5.31	0.183	0.209	
A1	2.21	2.59	0.087	0.102	
A2	1.50	2.49	0.059	0.098	
b	0.99	1.40	0.039	0.055	
b1	0.99	1.35	0.039	0.053	
b2	1.65	2.39	0.065	0.094	
b3	1.65	2.34	0.065	0.092	
С	0.38	0.89	0.015	0.035	
c1	0.38	0.84	0.015	0.033	
D	19.71	20.70	0.776	0.815	3
D1	13.08	-	0.515	-	4
D2	0.51	1.35	0.020	0.053	

Section C - C, D - D

SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
Е	15.29	15.87	0.602	0.625	3
E1	13.46	-	0.53	-	
е	5.46	BSC	0.215	BSC	
ØK	0.2	0.254 0.010		10	
L	19.81	20.32	0.780	0.800	
L1	3.71	4.29	0.146	0.169	
ØΡ	3.56	3.66	0.14	0.144	
Ø P1	-	6.98	-	0.275	
Q	5.31	5.69	0.209	0.224	
R	4.52	5.49	0.178	0.216	
S	5.51 BSC		0.217	BSC	
	•		•	•	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5M-1994
- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. These dimensions are measured at the outermost extremes of the plastic body
- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1
- (6) Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- (7) Outline conforms to JEDEC® outline TO-247 with exception of dimension A min., D, E min., Q min., S, and note 4



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